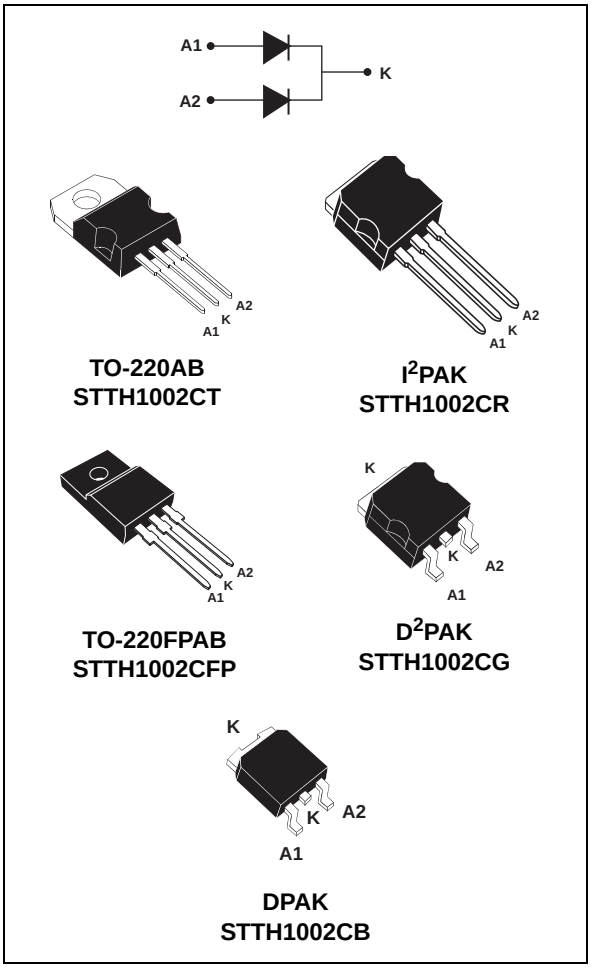
STTH1002C

High efficiency ultrafast diode

Datasheet - production data



TO-220AB
STTH1002CT

I²PAK
STTH1002CR

TO-220FPAB
STTH1002CFP

D²PAK
STTH1002CG

DPAK
STTH1002CB

Features

- Suited for SMPS
- Low losses
- Low forward and reverse recovery times
- Insulated package: TO-220FPAB
- High junction temperature
- Low leakage current

Description

Dual center tap rectifier suited for switch mode power supplies and high frequency DC to DC converters.

Packaged in DPAK, D²PAK, TO-220AB, TO220-FPAB and I²PAK, this device is intended for use in low voltage, high frequency inverters, free wheeling and polarity protection applications.

Table 1. Device summary

Symbol	Value
$I_{F(AV)}$	Up to 2 x 8 A
V_{RRM}	200 V
T_j (max)	175 °C
V_F(typ)	0.78 V
t_{rr} (typ)	20 ns

1 Characteristics

Table 2. Absolute ratings (limiting values, per diode)

Symbol	Parameter				Value	Unit
V_{RRM}	Repetitive peak reverse voltage				200	V
$I_{F(RMS)}$	Forward rms current	TO-220AB / TO-220FPAB / ^{2}PAK / D^{2}PAK			20	A
		DPAK			10	
$I_{F(AV)}$	Average forward current δ = 0.5	I^2PAK, D^{2}PAK, DPAK TO-220AB	T_c = 155 °C	Per diode	5	A
			T_c = 150 °C	Per device	10	
			T_c = 135 °C	Per diode	8	
			T_c = 125 °C	Per device	16	
		TO-220FPAB	T_c = 140 °C	Per diode	5	
			T_c = 120 °C	Per device	10	
			T_c = 110 °C	Per diode	8	
			T_c = 75 °C	Per device	16	A
I_{FSM}	Surge non repetitive forward current		t_p = 10 ms sinusoidal		50	A
T_{stg}	Storage temperature range				-65 to + 175	°C
T_j	Maximum operating junction temperature				175	°C

Table 3. Thermal parameters

Symbol	Parameter			Value (max)	Unit
$R_{th(j-c)}$	Junction to case	DPAK, I^2PAK, D^{2}PAK, TO-220AB	Per diode	4.0	°C/W
			Per device	2.5	
		TO-220FPAB	Per diode	6.5	
			Per device	5	
$R_{th(j-c)}$	Coupling	DPAK, I^2PAK, D^{2}PAK, TO-220AB		1.0	
		TO-220FPAB		3.5	

When the diodes 1 and 2 are used simultaneously:

ΔT_j (diode1) = P(diode1) x $R_{th(j-c)}$ (per diode) + P(diode2) x $R_{th(c)}$

Table 4. Static electrical characteristics (per diode)

Symbol	Parameter	Test conditions		Min.	Typ.	Max.	Unit
I_R(1)	Reverse leakage current	T_j = 25 °C	$V_R = V_{RRM}$			5	µA
		T_j = 125 °C			3	40	
V_F(2)	Forward voltage drop	T_j = 25 °C	I_F = 5 A			1.1	V
		T_j = 25 °C	I_F = 10 A			1.25	
		T_j = 150 °C	I_F = 5 A		0.78	0.89	
		T_j = 150 °C	I_F = 10 A			1.05	

1. Pulse test: t_p = 5 ms, δ < 2%
2. Pulse test: t_p = 380 µs, δ < 2%

To evaluate the conduction losses use the following equation:

$P = 0.73 \times I_{F(AV)} + 0.032\ I_F{}^2{}_{(RMS)}$

Table 5. Dynamic electrical characteristics

Symbol	Parameter	Test conditions		Min.	Typ.	Max.	Unit
t_{rr}	Reverse recovery time	T_j = 25 °C	I_F = 1 A, V_R = 30 V dI_F/dt = 100 A/µs		20	25	ns
I_{RM}	Reverse recovery current	T_j = 125 °C	I_F = 5 A, V_R = 160 V dI_F/dt = 200 A/µs		5.9	7.6	A
t_{fr}	Forward recovery time	T_j = 25 °C	I_F = 5 A, dI_F/dt = 100 A/µs $V_{FR} = 1.1 \times V_{Fmax}$			110	ns
V_{FP}	Forward recovery voltage	T_j = 25 °C	I_F = 5 A, dI_F/dt = 100 A/µs		2.4		V

Figure 1. Peak current versus duty cycle (per diode)

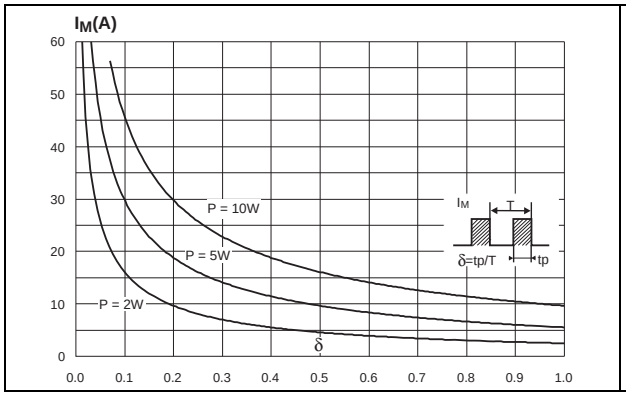


Figure 2. Forward voltage drop versus forward current (typical values, per diode)

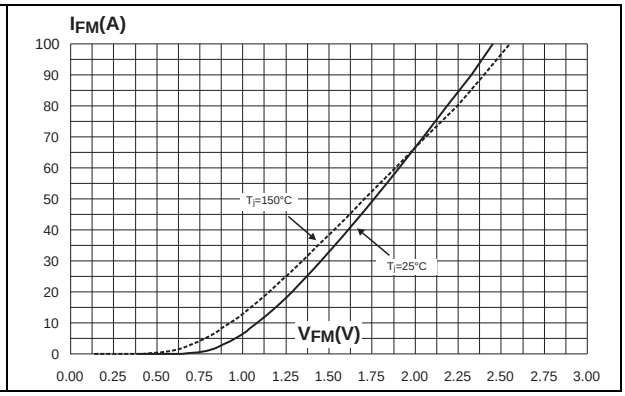


Figure 3. Forward voltage drop versus forward current (maximum values, per diode)

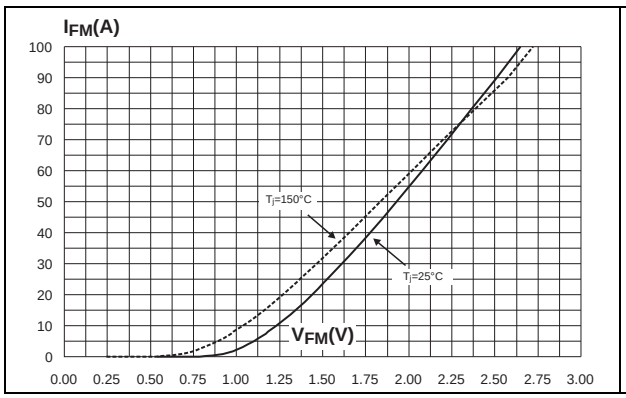


Figure 4. Relative variation of thermal impedance junction to case versus pulse duration

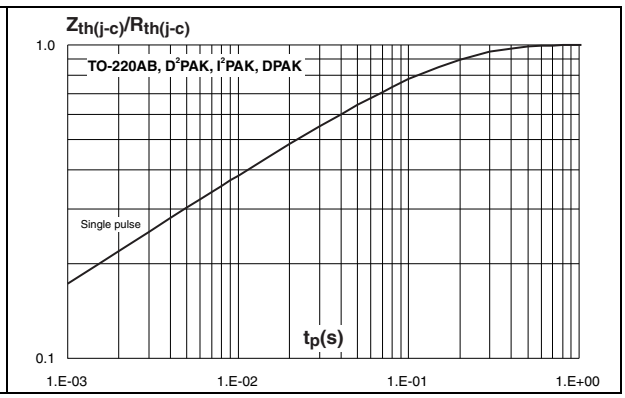


Figure 5. Relative variation of thermal impedance junction to case versus pulse duration (TO-220FPAB)

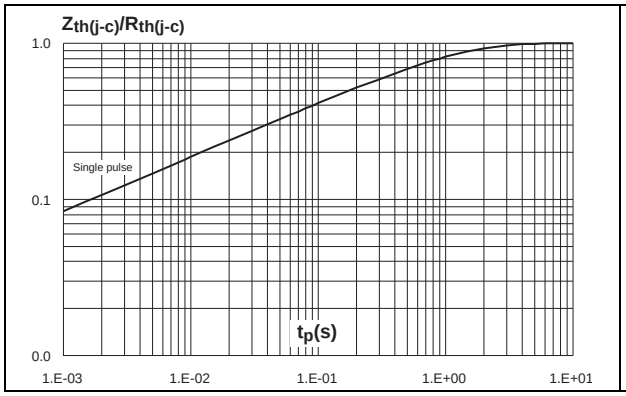


Figure 6. Junction capacitance versus reverse voltage applied (typical values, per diode)

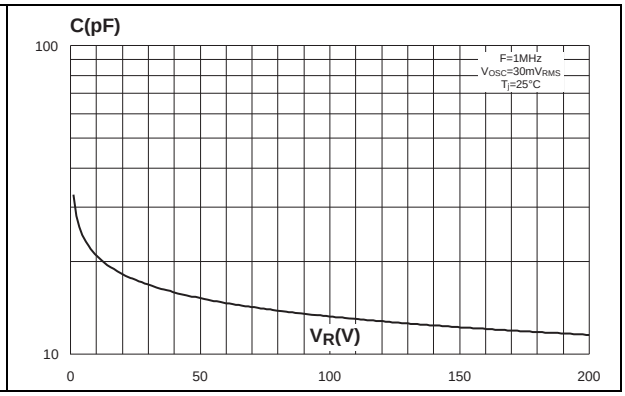


Figure 7. Reverse recovery charges versus dI_F/dt (typical values, per diode)

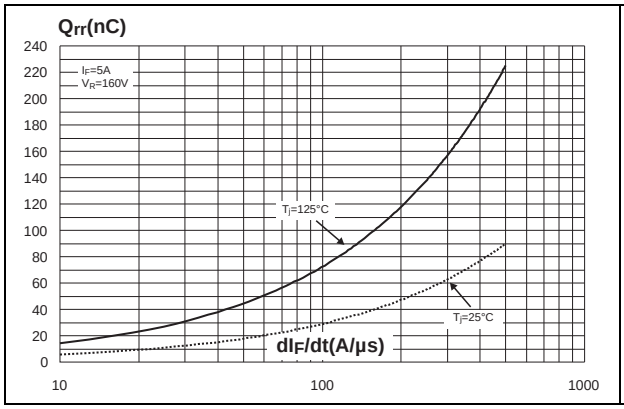


Figure 8. Reverse recovery time versus dI_F/dt (typical values, per diode)

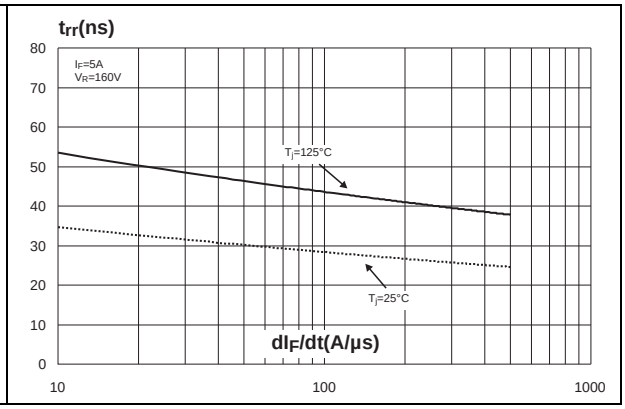


Figure 9. Peak reverse recovery current versus dI_F/dt (typical values, per diode)

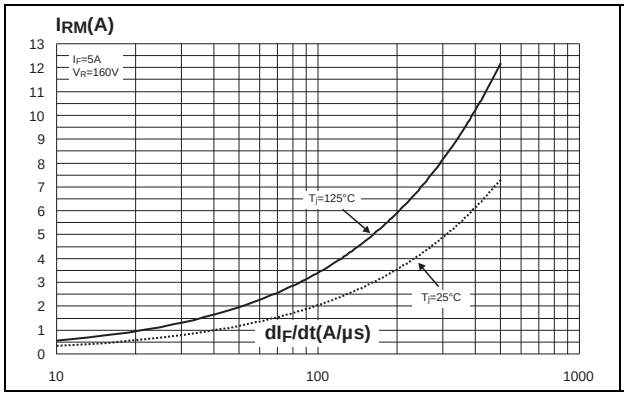


Figure 10. Dynamic parameters versus junction temperature

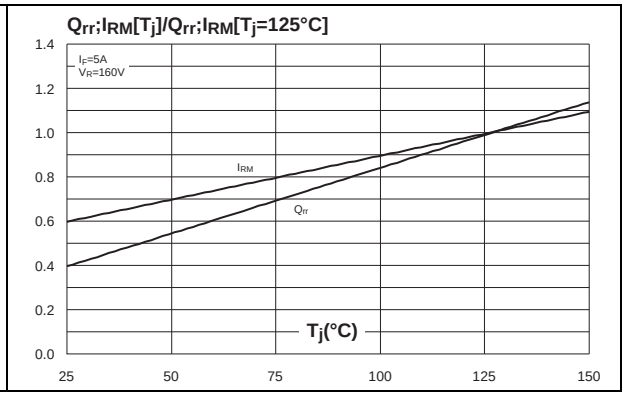


Figure 11. Thermal resistance junction to ambient versus copper surface under tab, D^2PAK

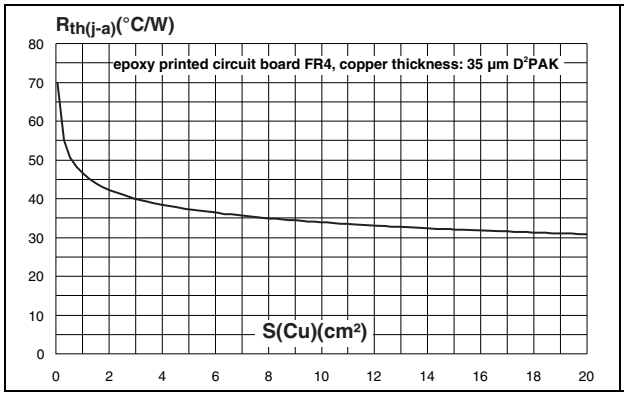
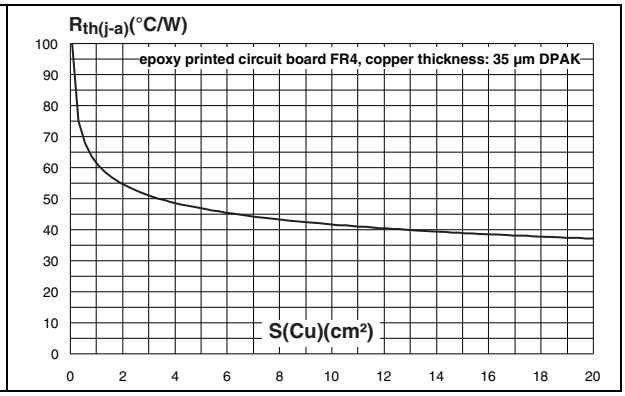


Figure 12. Thermal resistance junction to ambient versus copper surface under tab, DPAK



2 Package mechanical data

- Epoxy meets UL94, V0
- Cooling method: by conduction (method C)
- Recommended torque value: 0.4 to 0.6 N·m

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: *www.st.com*. ECOPACK® is an ST trademark.

Figure 13. DPAK dimension definitions

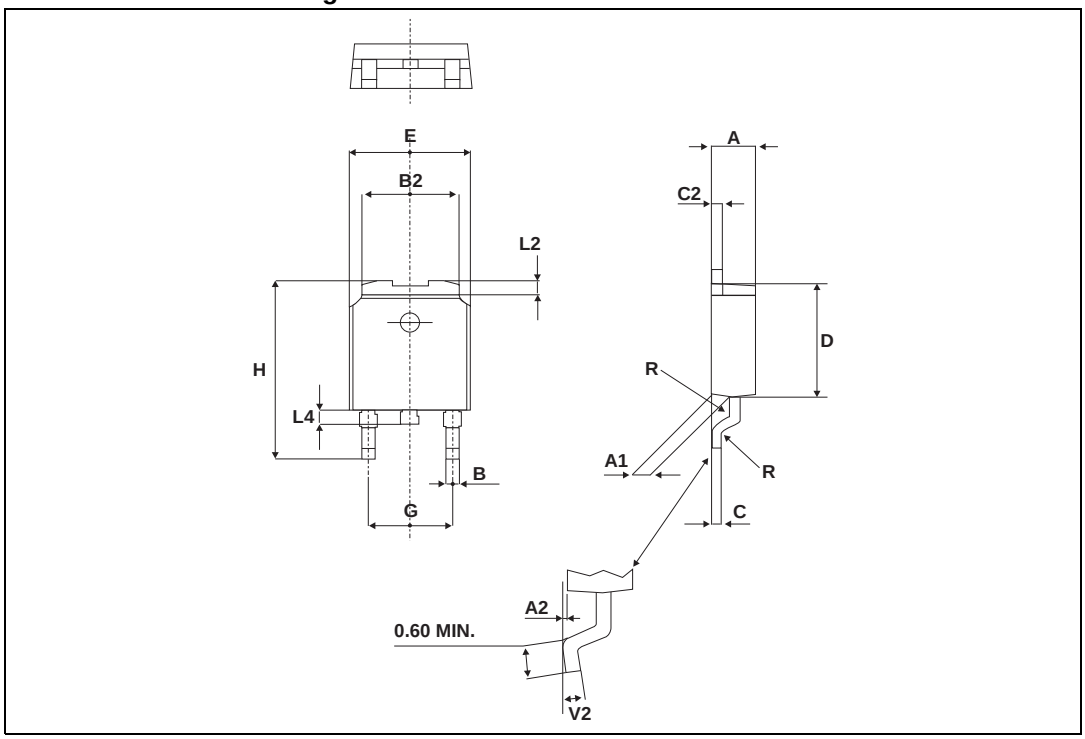
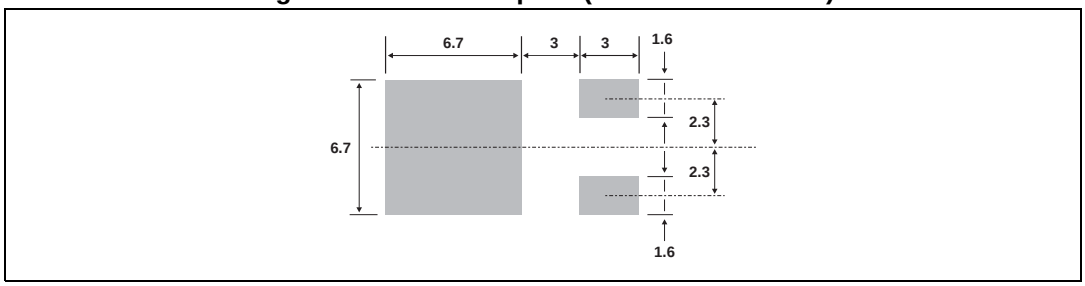


Table 6. DPAK dimension values

Ref.	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	2.20	2.40	0.086	0.094
A1	0.90	1.10	0.035	0.043
A2	0.03	0.23	0.001	0.009
B	0.64	0.90	0.025	0.035
B2	5.20	5.40	0.204	0.212
C	0.45	0.60	0.017	0.023
C2	0.48	0.60	0.018	0.023
D	6.00	6.20	0.236	0.244
E	6.40	6.60	0.251	0.259
G	4.40	4.60	0.173	0.181
H	9.35	10.10	0.368	0.397
L2	0.80 typ.		0.031 typ.	
L4	0.60	1.00	0.023	0.039
V2	0°	8°	0°	8°

Figure 14. DPAK footprint (dimensions in mm)



Devices in I^2PAK with nickel-plated back frame must NOT be mounted by frame soldering like SMDs. Such devices are intended to be through-hole mounted ONLY and in no circumstances shall ST be held liable for any lack of performance or damage arising out of soldering of nickel-plated back frames.

Figure 15. I^2PAK dimension definitions

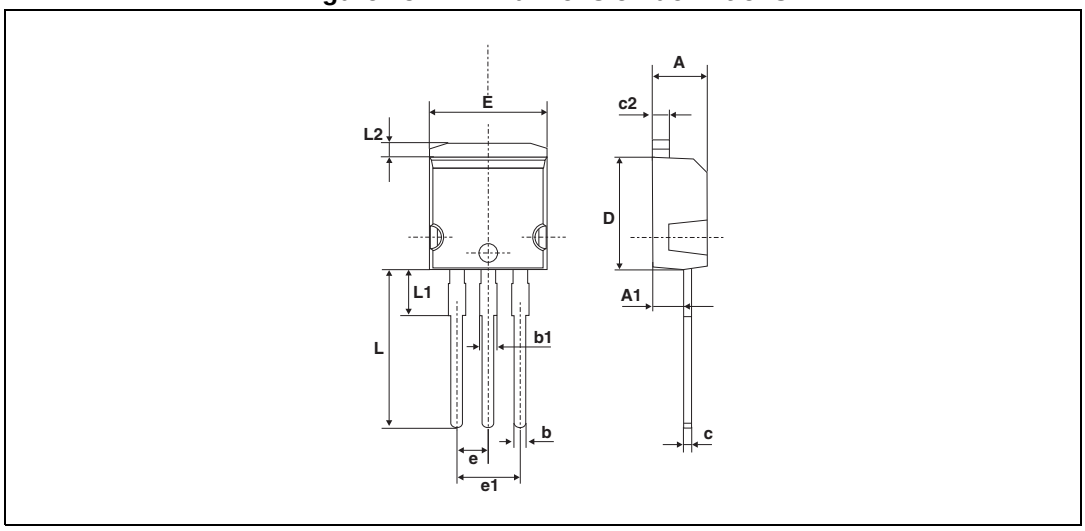


Table 7. I^2PAK dimension values

Ref.	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	4.40	4.60	0.173	0.181
A1	2.40	2.72	0.094	0.107
b	0.61	0.88	0.024	0.035
b1	1.14	1.70	0.044	0.067
c	0.49	0.70	0.019	0.028
c2	1.23	1.32	0.048	0.052
D	8.95	9.35	0.352	0.368
e	2.40	2.70	0.094	0.106
e1	4.95	5.15	0.195	0.203
E	10	10.40	0.394	0.409
L	13	14	0.512	0.551
L1	3.50	3.93	0.138	0.155
L2	1.27	1.40	0.050	0.055

Figure 16. D²PAK dimension definitions

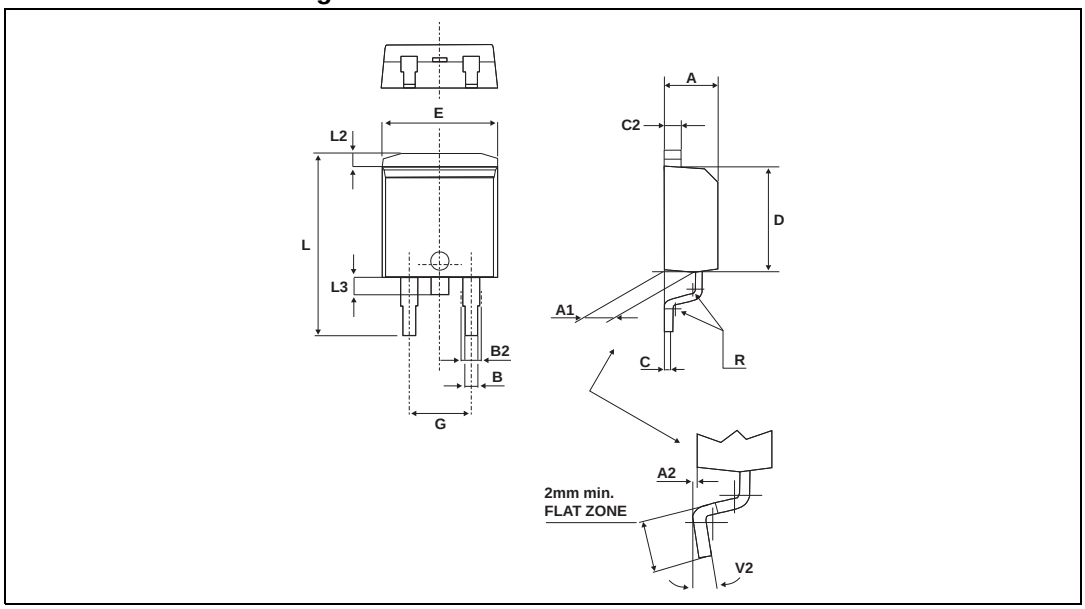


Table 8. D²PAK dimension values

Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	4.30		4.60	0.169		0.181
A1	2.49		2.69	0.098		0.106
A2	0.03		0.23	0.001		0.009
B	0.70		0.93	0.027		0.037
B2	1.25	1.40		0.048	0.055	
C	0.45		0.60	0.017		0.024
C2	1.21		1.36	0.047		0.054
D	8.95		9.35	0.352		0.368
E	10.00		10.28	0.393		0.405
G	4.88		5.28	0.192		0.208
L	15.00		15.85	0.590		0.624
L2	1.27		1.40	0.050		0.055
L3	1.40		1.75	0.055		0.069
R	0.40			0.016		
V2	0°		8°	0°		8°

Figure 17. D^{2}PAK footprint (dimensions in mm)

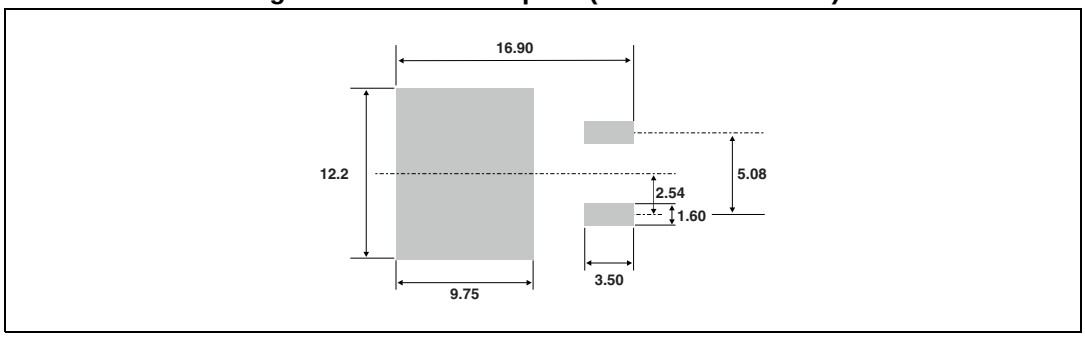
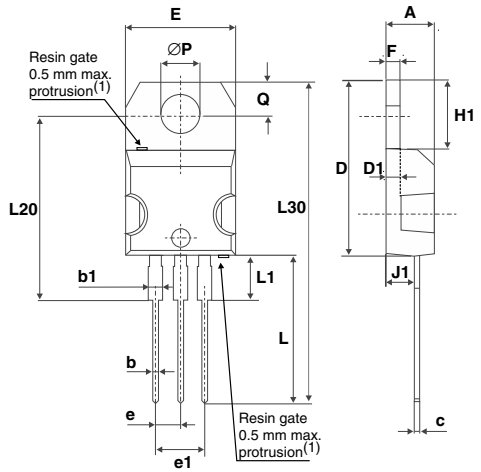


Figure 18. TO-220AB dimension definitions



(1) Resin gate position accepted in each of the two position shown as well as the symmetrical opposites

Table 9. TO-220AB dimension values

Ref.	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	4.40	4.60	0.17	0.18
b	0.61	0.88	0.024	0.035
b1	1.14	1.70	0.045	0.067
c	0.48	0.70	0.019	0.027
D	15.25	15.75	0.60	0.62
D1	1.27 typ.		0.05 typ.	
E	10	10.40	0.39	0.41
e	2.40	2.70	0.094	0.106
e1	4.95	5.15	0.19	0.20
F	1.23	1.32	0.048	0.052
H1	6.20	6.60	0.24	0.26
J1	2.40	2.72	0.094	0.107
L	13	14	0.51	0.55
L1	3.50	3.93	0.137	0.154
L20	16.40 typ.		0.64 typ.	
L30	28.90 typ.		1.13 typ.	
ØP	3.75	3.85	0.147	0.151
Q	2.65	2.95	0.104	0.116

Figure 19. TO-220FPAB dimension definitions

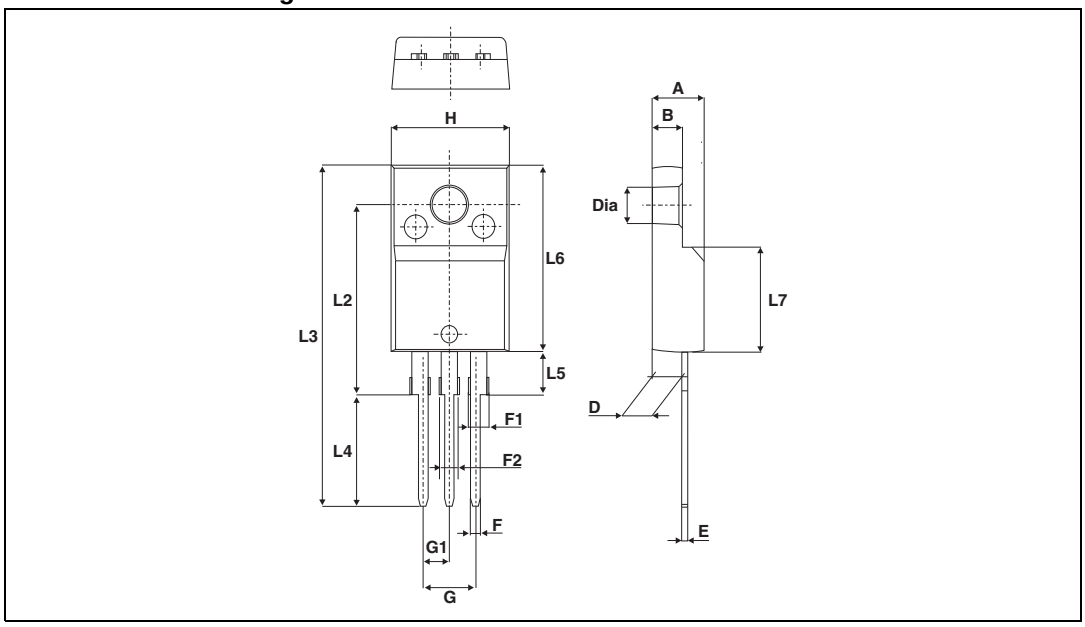


Table 10. TO-220FPAB dimension values

Ref.	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	4.4	4.6	0.173	0.181
B	2.5	2.7	0.098	0.106
D	2.5	2.75	0.098	0.108
E	0.45	0.70	0.018	0.027
F	0.75	1	0.030	0.039
F1	1.15	1.70	0.045	0.067
F2	1.15	1.70	0.045	0.067
G	4.95	5.20	0.195	0.205
G1	2.4	2.7	0.094	0.106
H	10	10.4	0.393	0.409
L2	16 Typ.		0.63 Typ.	
L3	28.6	30.6	1.126	1.205
L4	9.8	10.6	0.386	0.417
L5	2.9	3.6	0.114	0.142
L6	15.9	16.4	0.626	0.646
L7	9.00	9.30	0.354	0.366
Dia.	3.00	3.20	0.118	0.126

3 Ordering information

Table 11. Ordering information

Order code	Marking	Package	Weight	Base qty	Delivery mode
STTH1002CB	STTH1002CB	DPAK	0.3 g	75	Tube
STTH1002CB-TR	STTH1002CB	DPAK	0.3 g	2500	Tape and reel
STTH1002CT	STTH1002CT	TO-220AB	2.23 g	50	Tube
STTH1002CG-TR	STTH1002CG	D^2PAK	1.48 g	1000	Tape ad reel
STTH1002CR	STTH1002CR	I^2PAK	1.49 g	50	Tube
STTH1002CFP	STTH1002CFP	TO-220AB	1.70 g	50	Tube

4 Revision history

Table 12. Document revision history

Date	Revision	Changes
Mar-2004	4	Last issue.
22-Mar-2013	5	Updated *Table 7.*

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